## **UNR32A1**

## Silicon NPN epitaxial planar transistor

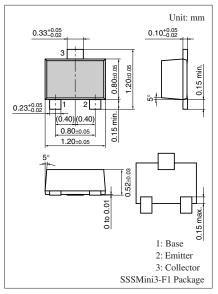
#### For digital circuits

#### ■ Features

- Suitable for high density package and downsizing of the equipment
- Contribute to low power consumption

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Rating	Collector to base voltage	$V_{CBO}$	50	V	
of	Collector to emitter voltage	$V_{CEO}$	50	V	
element	Collector current	$I_C$	80	mA	
Overall	Total power dissipation	$P_{T}$	100	mW	
	Junction temperature	$T_{j}$	125	°C	
	Storage temperature	$T_{stg}$	-55 to +125	°C	



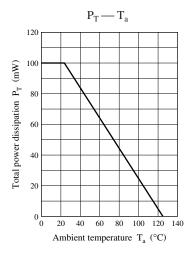
Marking Symbol: FK

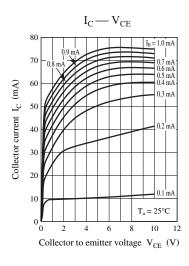
#### Internal Connection

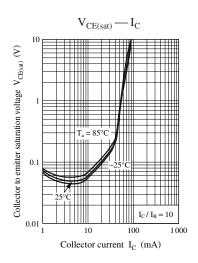
$$\begin{array}{c}
R_1 (10 k\Omega) \\
B \circ \longrightarrow W \\
R_2 \\
(10 k\Omega)
\end{array}$$
 $\circ$  C

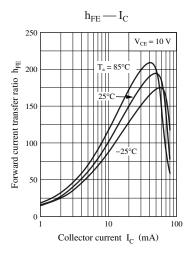
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

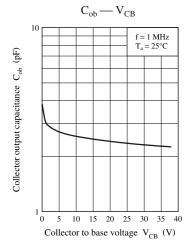
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector to base voltage	$V_{CBO}$	$I_C = 10 \ \mu A, I_E = 0$	50			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector cutoff current	$I_{CBO}$	$V_{CB} = 50 \text{ V}, I_{E} = 0$			0.1	μΑ
	I <sub>CEO</sub>	$V_{CE} = 50 \text{ V}, I_{B} = 0$			0.5	
Emitter cutoff current	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_{C} = 0$			0.5	mA
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	35			_
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$			0.25	V
High level output voltage	V <sub>OH</sub>	$V_{CC} = 5 \text{ V}, V_B = 0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	4.9			V
Low level output voltage	V <sub>OL</sub>	$V_{CC} = 5 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			0.2	V
Input resistance	R <sub>1</sub>		-30%	10	+30%	kΩ
Resistance ratio	R <sub>1</sub> / R <sub>2</sub>		0.8	1.0	1.2	_
Gain bandwidth product	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

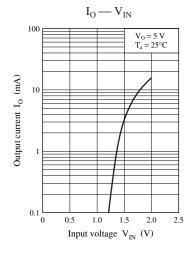


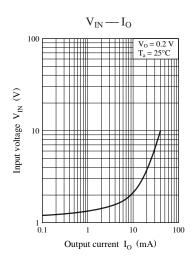












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